IODATE-CONTAINING CHEMICAL-MECHANICAL POLISHING COMPOSITIONS AND METHODS

ABSTRACT

The invention provides compositions and methods for planarizing or polishing a substrate. The composition comprises an abrasive, iodate ion, a nitrogen-containing compound selected from the group consisting of a nitrogen-containing C_{4-20} heterocycle and a C_{1-20} alkylamine, and a liquid carrier comprising water.

Figure 1